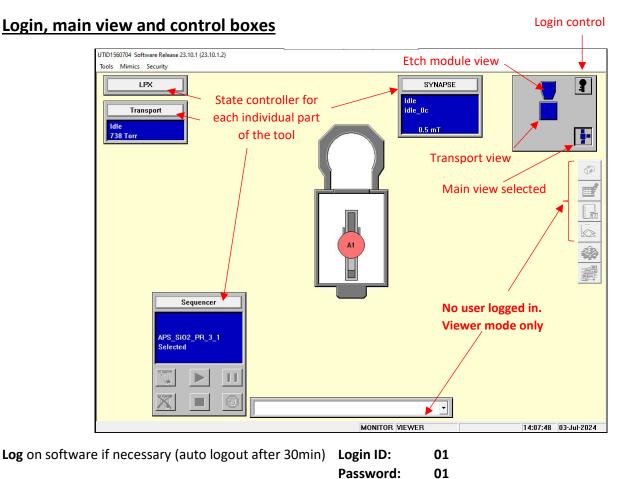
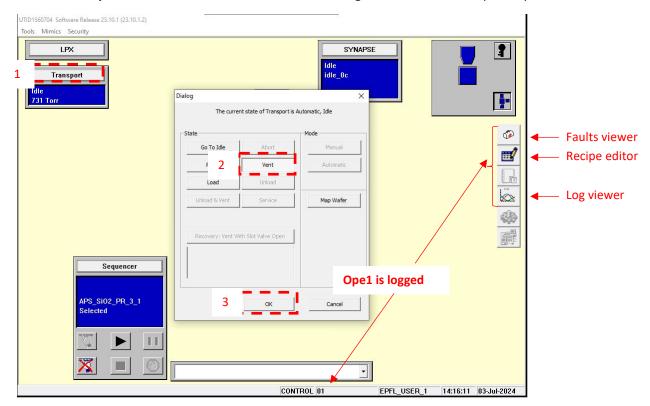
SPTS Synapse Dielectrics Etcher



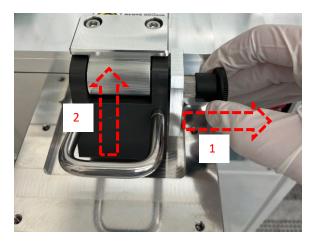
Select the **main view** as starting point.

Click 1 "Transport", 2 "Vent" and 3 "OK" in order to bring the loader to atmospheric pressure.

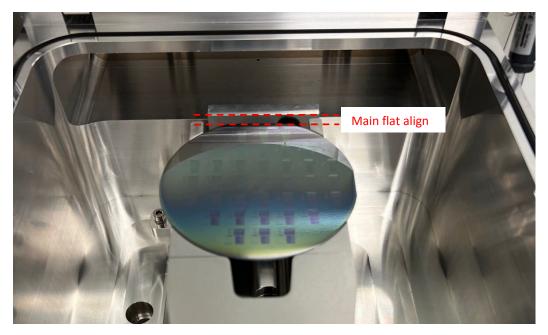


Loading the wafer

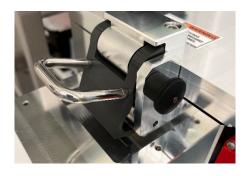
When at air, 1 unlock the loader by pulling on the black knob and 2 lift the cover up

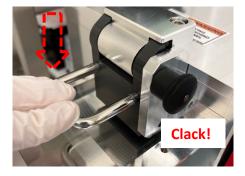


Load the wafer with its **main flat facing the rear of the loader**. Wafer rotation alignment is done visually.



Close the cover and lock it

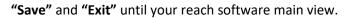




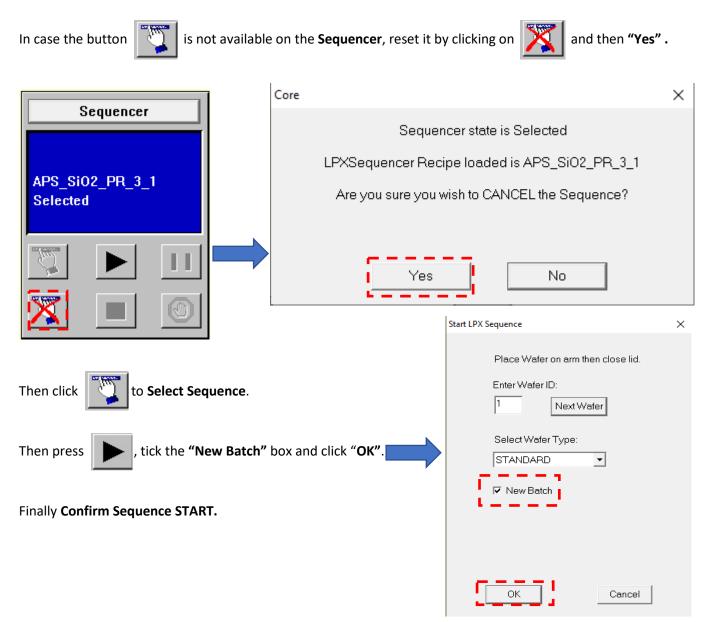
Recipe edition

Open the recipe editor, select **1 "Process" & 2 "Module"** type recipe, **3 "Synapse"** module and **4 "Development"** classification to shorten the list with only recipes of interest. **5 Select your recipe** in the list and click **6 "Open"**.

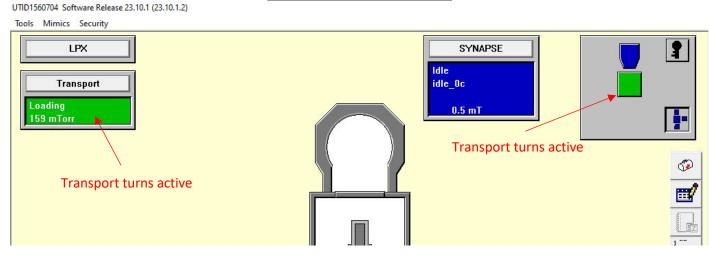
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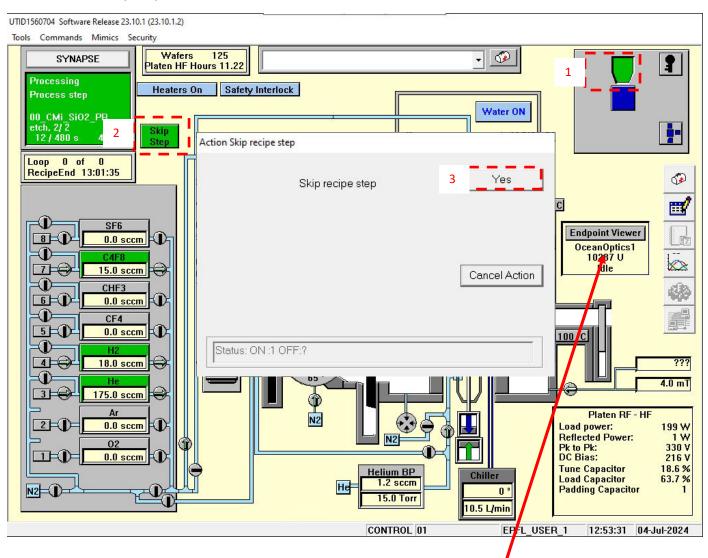
Recipe start – from main view



Transport will turn green until the wafer is fully loaded in the Synapse chamber.



During the process, it is possible to stop the etch anytime when **Skip Step** is available: **1 Select Synapse module view**, click the **2 Skip Step** button, and **3 confirm the action.**



The system is fitted with integrated OES end-point system. Click on **"Endpoint Viewer" OceanOptics1** to open vision of the registered curve.

After etch, the Synapse chamber may auto-clean while the loader returns to atmospheric pressure. If so, just wait for the auto-clean to complete automatically (not action required).

When finished with the tool, close the cover and lock it. And return the Transport to Vacuum

